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A

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IC - C08G12/06 ; C08G14/06 ; C08G59/50 ; C08G73/02 ; C09D3/58

MC - A05-A01B A08-D01

M3 - [01] K0 H1 M311 M312 M313 M314 M315 M316 M332 M334 M322 M323 M280 M342
M340 M380 M392 M393 L420 H182 H183 M620 Q110 Q120 M510 M520 M530 M540

M782 R043 M416 M902

- [02] H4 M121 M129 M132 M135 M139 M149 M312 M313 M314 M315 M316 M332
M331 M334 M333 M321 M280 M342 M343 M344 G100 M150 M533 M532 H442 H443
H444 Q110 Q120 H402 H403 H404 H405 M510 H8 M520 M540 M782 R043 M414

M902

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PN - JP51082400 A 19760719 DW197636 000pp

- JP57031575B B 19820706 DW198230 000pp

PR - JP19750007609 19750117

XIC - C08G-012/06 ; C08G-014/06 ; C08G-059/50 ; C08G-073/02 ; C09D-003/58

AB - J51082400 The compsn. contains (I) an epoxy resin having an av. of >1
adjacent epoxy gp. per molecule and (II) an active organic amino cpd,
obtd. by reacting a polyamine having is not <2 amino gps. having an
amt. of >=1 active H attached to the N atom per molecule in average,
(b) thiourea or ammonium thiocyanate, (c) a phenol having >=1 hydroxyl
gp. attached to an aromatic nucleus with >=1 aromatic reactive
positions not being substd. with other than H and of a carbonyl cpd.
having >=1 carbonyl gp. per molecule.

IW - QUICK HARDEN FILM FORMING EPOXY RESIN LOW HIGH TEMPERATURE

IKW - QUICK HARDEN FILM FORMING EPOXY RESIN LOW HIGH TEMPERATURE

NC - 001

OPD - 1975-01-17

ORD - 1976-07-19

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T1 - Quick hardening film-forming epoxy resin compn - at low and high temps

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Quick hardening film-forming epoxy resin compn - at low and high temps

Patent Assignee: ASAHI DENKA KOGYO KK (ASAE)

Number of Countries: 001 Number of Patents: 002

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date
JP 51082400	A	19760719			
197636	B				
JP 82031575	B	19820706			
		198230			

Priority Applications (No Type Date): JP 757609 A 19750117

Abstract (Basic): JP 51082400 A

The compsn. contains (I) an epoxy resin having an av. of >1 adjacent epoxy gp. per molecule and (II) an active organic amino cpd. obtd. by reacting a polyamine having is not <2 amino gps. having an amt. of >=1 active H attached to the N atom per molecule in average, (b) thiourea or ammonium thiocyanate, (c) a phenol having >=1 hydroxyl gp. attached to an aromatic nucleus with >=1 aromatic reactive positions not being substd. with other than H and of a carbonyl cpd. having >=1 carbonyl gp. per molecule.

Derwent Class: A21; E14

International Patent Class (Additional): C08G-012/06; C08G-014/06;

C08G-059/50; C08G-073/02; C09D-003/58